



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

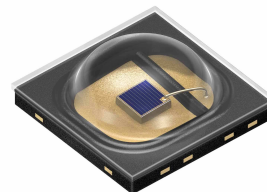
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SFH 4714A



Features:

- IR lightsource with high efficiency
- Low thermal resistance (Max. 16 K/W)
- Centroid wavelength 850 nm
- Superior Corrosion Robustness (see chapter package outlines)

Applications

- Infrared Illumination for cameras
- Surveillance systems
- Machine vision systems
- Gesture recognition systems

Notes

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Ordering Information

Type:	Radiant Intensity I_e [mW/sr] $I_F = 1 \text{ A}, t_p = 10 \text{ ms}$	Ordering Code
SFH 4714A	165 (≥ 100)	Q65111A8234

Note: measured at a solid angle of $\Omega = 0.01 \text{ sr}$

Maximum Ratings ($T_A = 25\text{ °C}$)

Parameter	Symbol	Values	Unit
Operation and storage temperature range	$T_{op}; T_{stg}$	-40 ... 125	°C
Junction temperature	T_j	145	°C
Reverse voltage	V_R	5	V
Forward current	I_F	1000	mA
Surge current ($D \leq 1$)	I_{FSM}	1	A
Power consumption	P_{tot}	2.3	W
Thermal resistance junction - solder point	R_{thJS}	16	K / W
ESD withstand voltage (acc. to ANSI/ ESDA/ JEDEC JS-001 - HBM)	V_{ESD}	2	kV

Note: For the forward current and power consumption please see "maximum permissible forward current" diagram

Characteristics ($T_A = 25\text{ °C}$)

Parameter	Symbol	Values	Unit
Peak wavelength ($I_F = 1\text{ A}$, $t_p = 10\text{ ms}$)	(typ) λ_{peak}	860	nm
Centroid wavelength ($I_F = 1\text{ A}$, $t_p = 10\text{ ms}$)	(typ) $\lambda_{centroid}$	850	nm
Spectral bandwidth at 50% of I_{max} ($I_F = 1\text{ A}$, $t_p = 10\text{ ms}$)	(typ) $\Delta\lambda$	34	nm
Half angle	(typ) φ	± 75	°
Dimensions of active chip area	(typ) L x W	0.75 x 0.75	mm x mm
Rise and fall times of I_e (10% and 90% of $I_{e,max}$) ($I_F = 1\text{ A}$, $R_L = 50\ \Omega$)	(typ) t_r / t_f	11/ 15	ns
Forward voltage ($I_F = 1\text{ A}$, $t_p = 10\text{ ms}$)	(typ (max)) V_F	1.75 (≤ 2.3)	V
Reverse current ($V_R = 5\text{ V}$)	I_R	not designed for reverse operation	μA
Total radiant flux ($I_F = 1\text{ A}$, $t_p = 100\ \mu\text{s}$)	(typ) Φ_e	760	mW
Total radiant flux ($I_F = 1\text{ A}$, $t_p = 10\text{ ms}$)	(typ) Φ_e	745	mW

Parameter		Symbol	Values	Unit
Temperature coefficient of I_e or Φ_e ($I_F = 1$ A, $t_p = 10$ ms)	(typ)	TC_I	-0.3	% / K
Temperature coefficient of V_F ($I_F = 1$ A, $t_p = 10$ ms)	(typ)	TC_V	-1	mV / K
Temperature coefficient of wavelength ($I_F = 1$ A, $t_p = 10$ ms)	(typ)	TC_λ	0.3	nm / K

Grouping ($T_A = 25$ °C)

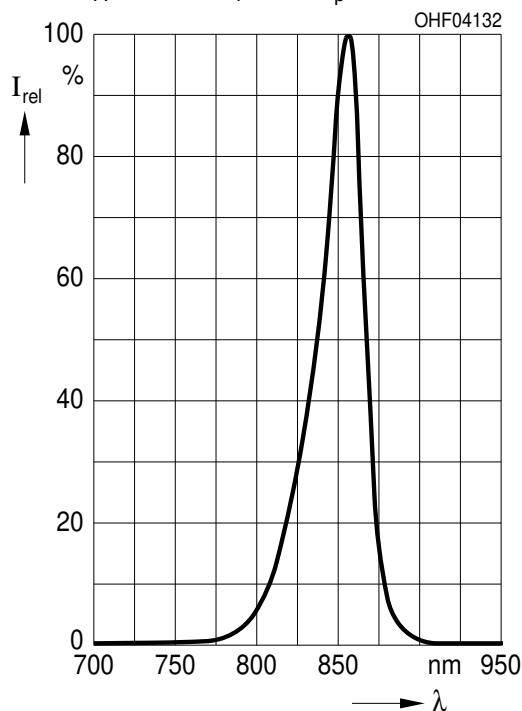
Group	Min Radiant Intensity	Max Radiant Intensity
	$I_F = 1$ A, $t_p = 10$ ms $I_{e, \min}$ [mW / sr]	$I_F = 1$ A, $t_p = 10$ ms $I_{e, \max}$ [mW / sr]
SFH 4714A -AA	100	160
SFH 4714A -AB	125	200
SFH 4714A -BA	160	250

Note: measured at a solid angle of $\Omega = 0.01$ sr

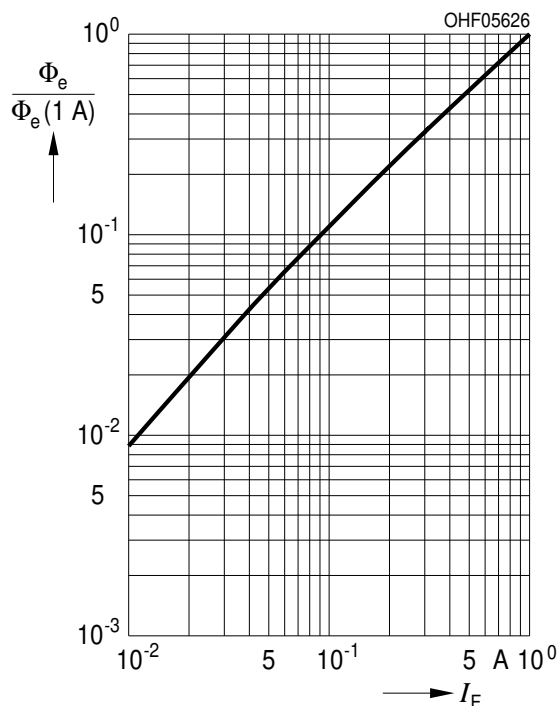
Only one group in one packing unit (variation lower 1.6:1).

Relative Spectral Emission ^{1) page 12}

$I_{rel} = f(\lambda)$, $T_A = 25$ °C, $I_F = 1$ A, $t_p = 10$ ms

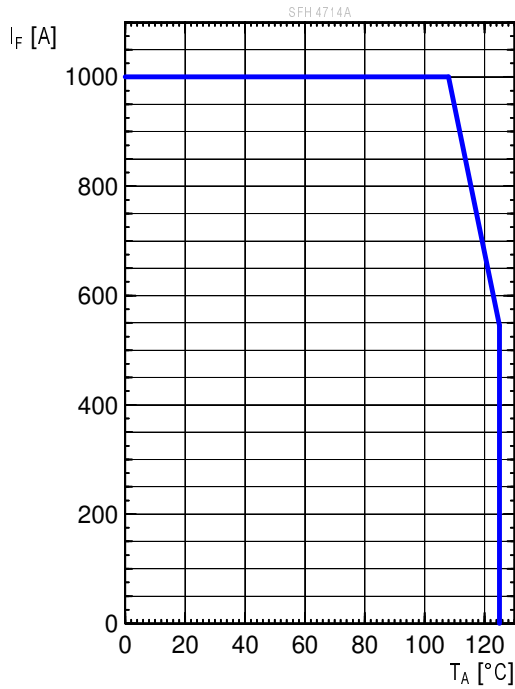
**Relative Total Radiant Flux** ^{1) page 12}

$\Phi_e / \Phi_e(1A) = f(I_F)$, $T_A = 25$ °C, Single pulse, $t_p = 100$ μ s



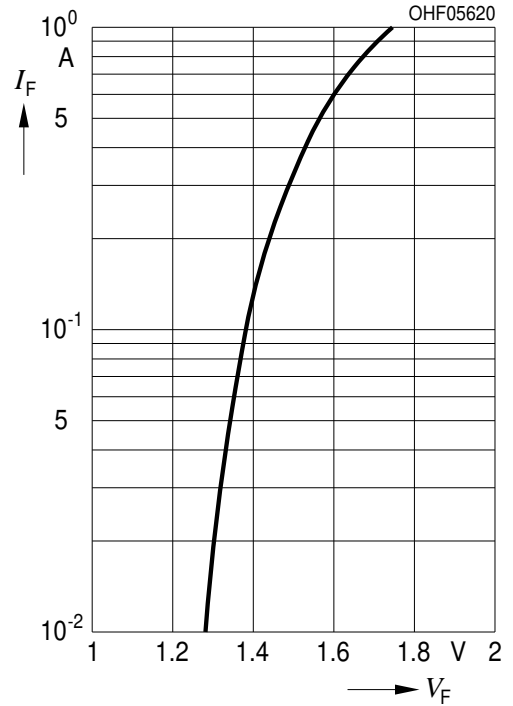
Max. Permissible Forward Current

$I_F = f(T_S), R_{thJS} = 16 \text{ K/W}$



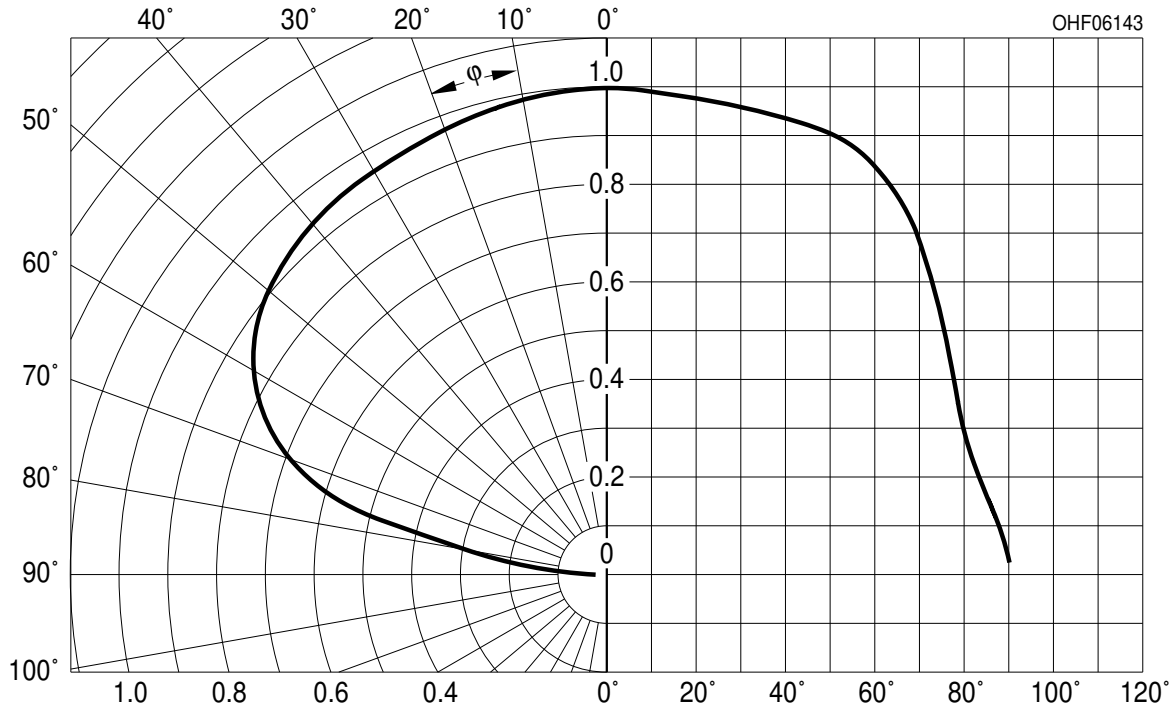
Forward Current ^{1) page 12}

$I_F = f(V_F), \text{ single pulse, } t_p = 100 \mu\text{s}, T_A = 25^\circ\text{C}$

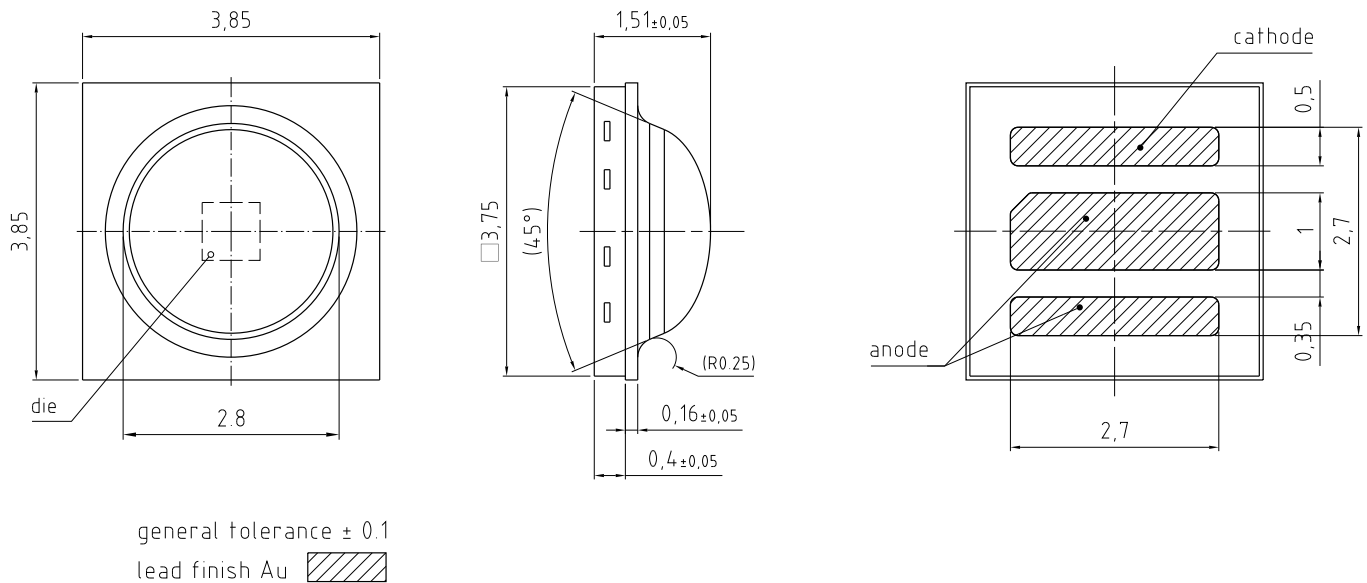


Radiation Characteristics ^{1) page 12}

$I_{rel} = f(\phi), T_A = 25^\circ\text{C}$



Package Outline



C63062-A4141-A10-02

Dimensions in mm.

Package

OSLON Black Series

Approximate Weight:

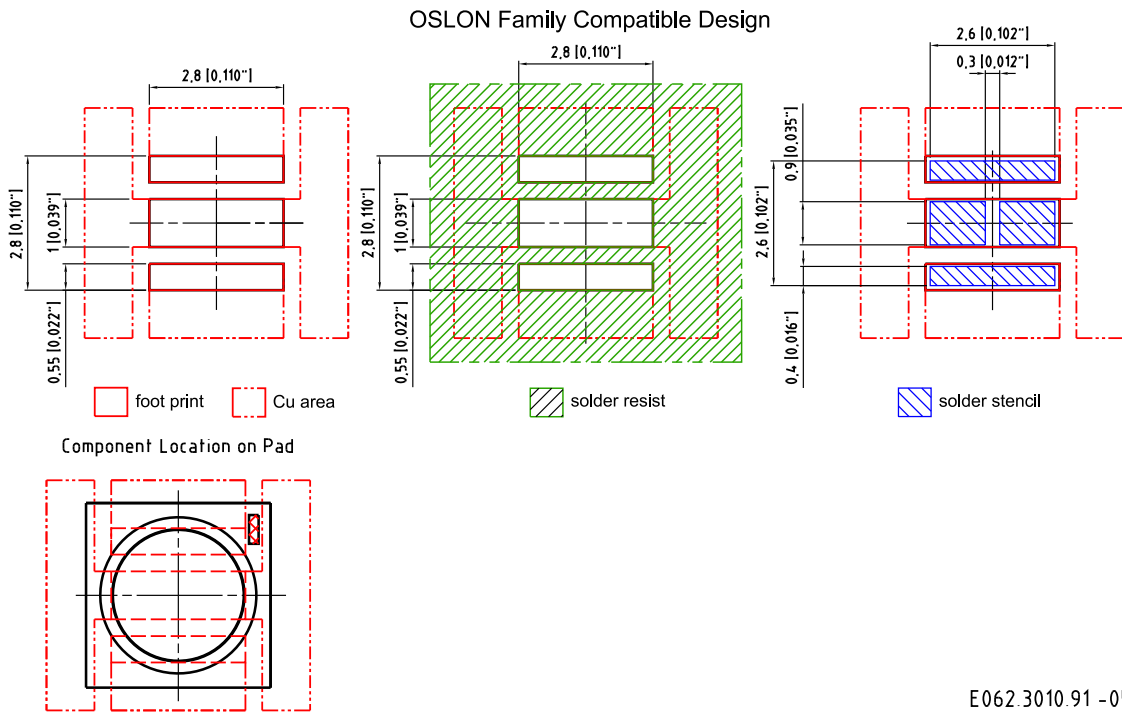
31 mg

Note:

Package is not suitable for ultra sonic cleaning.

Note:Corrosion robustness better than EN 60068-2-60 (method 4): with enhanced corrosion test: 40°C / 90%rh / 15ppm H₂S / 336h**Note:****Anode mark:** Anode pad has chamfered edge, which points to cathode

Recommended Solder Pad



E062.3010.91 -05

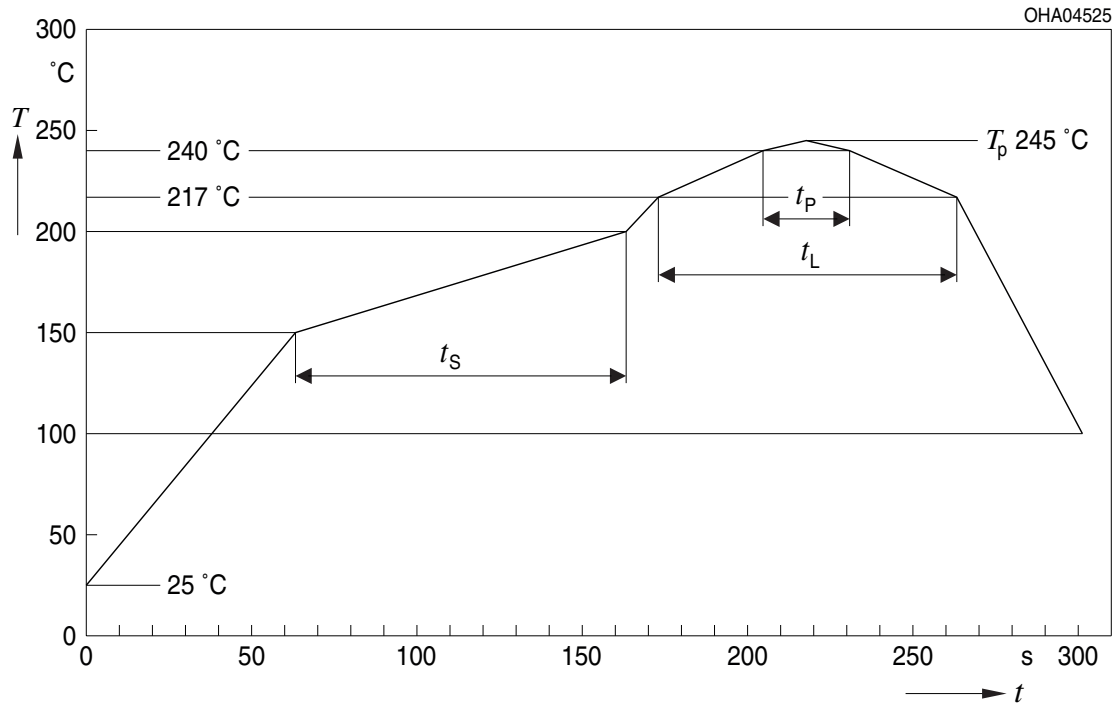
Dimensions in mm [inch].

Note:

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



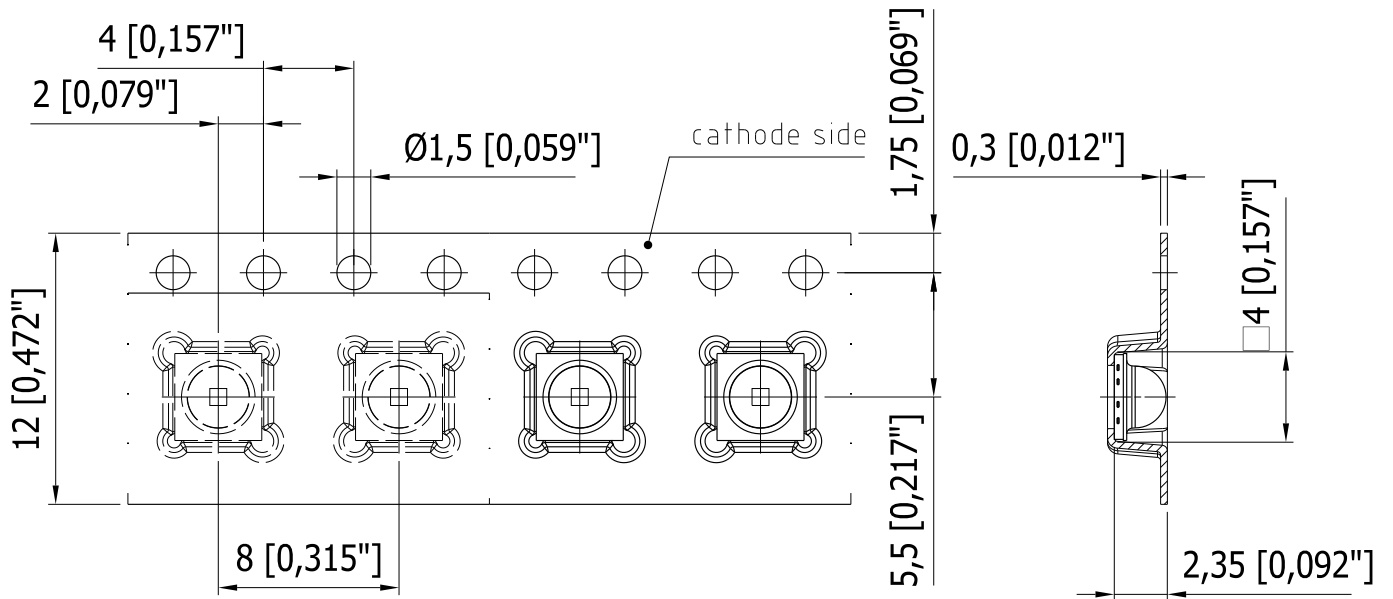
OHA04612

Profile Feature Profil-Charakteristik	Symbol Symbol	Pb-Free (SnAgCu) Assembly			Unit Einheit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature $T_P - 5$ K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping

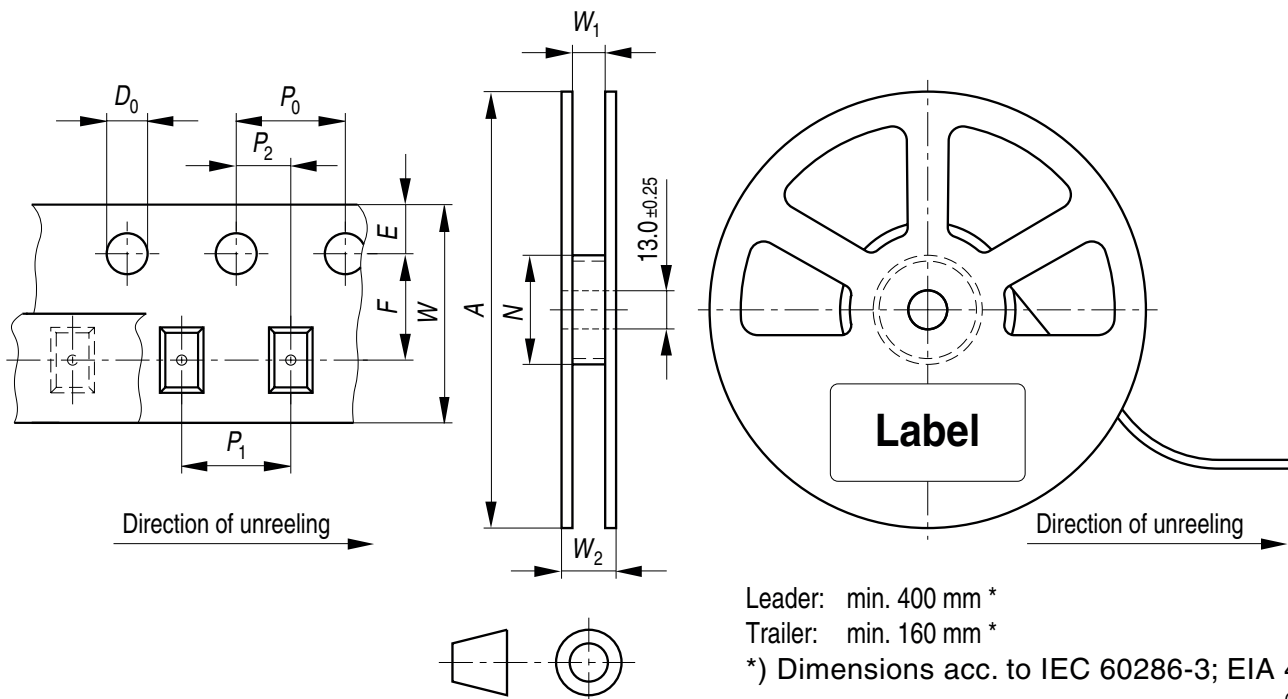


C63062-A4068-B12 -02

Dimensions in mm [inch].

Tape and Reel

12 mm tape with 600 pcs. on \varnothing 180 mm reel



Leader: min. 400 mm *

Trailer: min. 160 mm *

*) Dimensions acc. to IEC 60286-3; EIA 481-D

OHAY0324

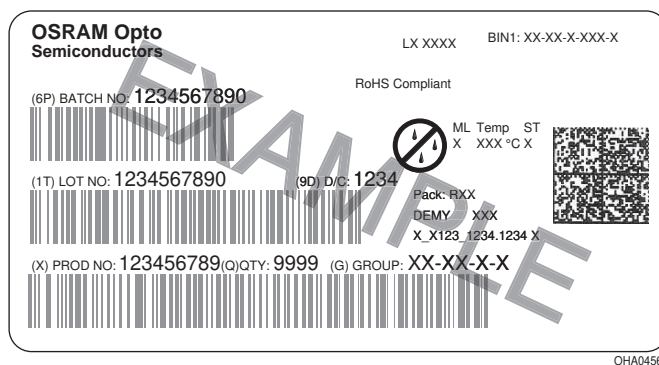
Tape dimensions [mm]

W	P ₀	P ₁	P ₂	D ₀	E	F
12 + 0.3 / - 0.1	4 ± 0.1	4 ± 0.1 or 8 ± 0.1	2 ± 0.05	1.5 ± 0.1	1.75 ± 0.1	5.5 ± 0.05

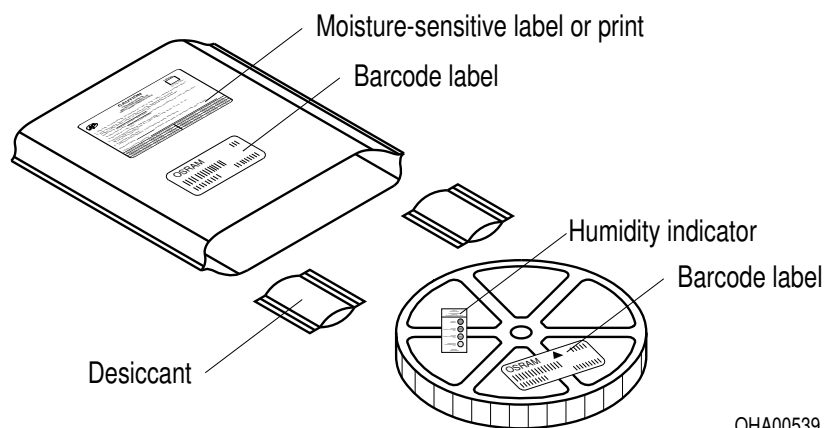
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2max}
180	12	60	12.4 + 2	18.4

Barcode-Product-Label (BPL)



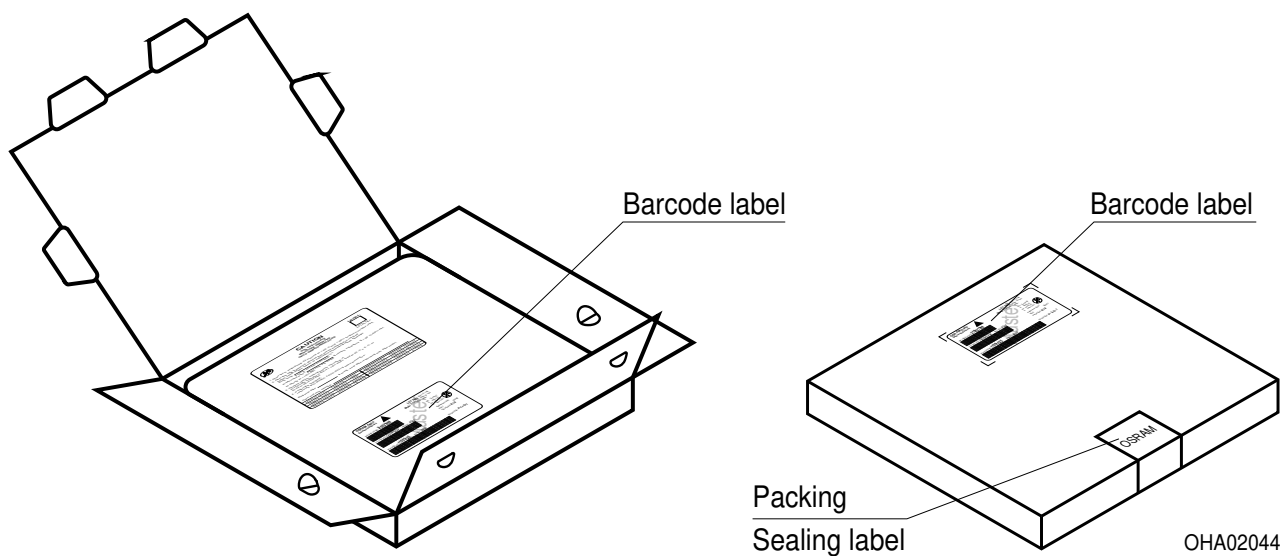
Dry Packing Process and Materials



Note:

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card. Regarding dry pack you will find further information in the internet. Here you will also find the normative references like JEDEC.

Transportation Packing and Materials



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5	195 ± 5	30 ± 5

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.

Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version in the Internet.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose!

Critical components* may only be used in life-support devices** or systems with the express written approval of OSRAM OS.

*) A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

**) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.

Glossary

- ¹⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

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